OKI Semiconductor

This version: Jan. 1998 Previous version: Nov. 1996

MSM6948/6948V

1200 bps Single Chip MSK Modem

GENERAL DESCRIPTION

The MSM6948/6948V is a single chip MSK (Minimum Shift Keying) modem which is fabricated by Oki's low power consumption CMOS silicon gate technology.

The demodulator receives the data to be transmitted (SD) synchronized with the transmit timing clock (ST) generated by the on-chip clock generator. The signal, which is modulated by MSK method, is output.

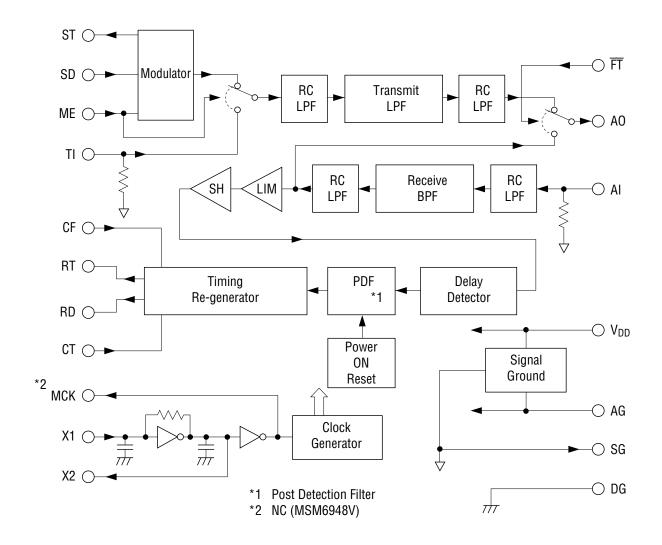
The demodulator converts the received MSK signal to the received data (RD) by means of a delay detection technique after limiting the band of the received MSK signal. This signal is input to the digital PLL and the re-generated timing clock (RT) is output from the demodulator, synchronized with the RD.

FEATURES

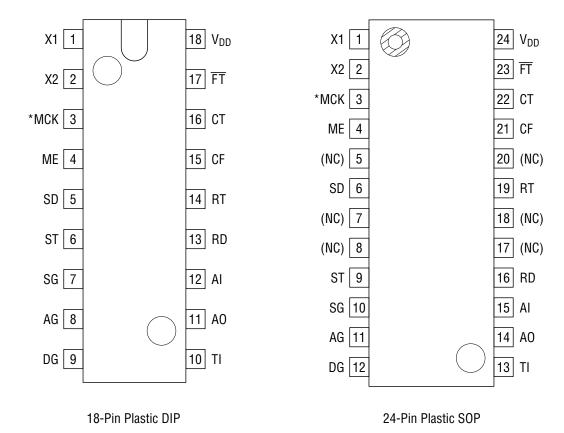
- Signal power supply: +5 V
- On-chip SCF (Switched Capacitor Filter)
- The transmit filter can be also used as voice splatter filter.
- The receive timing re-generator has two different lock-in time performance options to be chosen from.
- Built-in crystal oscillation circuit.
- Small number of external components for easy application.
- Wide application-wireless data equipment, MCA system.
- Low power consumption CMOS.
- Package options:

18-pin plastic DIP (DIP18-P-300-2.54) (Product name: MSM6948RS) 24-pin plastic SOP (SOP24-P-430-1.27-K) (Product name: MSM6948GS-K)

BLOCK DIAGRAM



PIN CONFIGURATION (TOP VIEW)



*NC (MSM6948V) NC : No connect pin

PIN DESCRIPTION

Name	Description
X1	Crystal connection pins. A 3.6864 MHz crystal shall be connected.
X2	When an external clock is applied for MSM6948's oscillation source, it has to be input to X2. In this case, X2 has to be AC-coupled by the capacitor of 200 pF. X1 shall be left open.
*MCK	3.6864 MHz ±0.02% clock output. This can be used for other devices under limited load conditions.
ME	When digital "1" is put on this pin, MSK modulator output is connected to the input of transmit LPF. When digital "0" is put on, the input of transmit LPF is connected to TI that is voice signal input. The data put on ME terminal is synchronized with the rising edge of ST and input to internal logic as a control data. The rising edge of this synchronized data resets MSK modulator.
SD	Transmit data input. The data on this pin is synchronized with the rising edge of ST and input to MSK modulator as an actual transmit data. SD
ST	ST is synchronizing signal used for ME and SD. This is made from master clock and is usually 1200 Hz.
SG	Built-in analog signal ground. The DC voltage is approximately half of V _{DD} , so the analog signals of AI, AO, and TI interfaces with peripheral circuits which must be implemented by AC-coupling. To make this voltage source impedance lower and ensure the device performance, it is necessary to put a bypass capacitor on SG in close physical proximity to the device.
AG	Analog ground. This pin should be common with DG at the system ground point as close as possible.

*NC: MSM6948V

Name			Description					
DG	Digital ground. This pin should be common with AG at the system ground point as close as possible.							
ТІ	Voice signal input. The signal input to this pin can be sent out to AO through the transmit LPF, the characteristics of which, gives the splatter filter for voice band signal. When this function is used, digital "0" must be input to ME. TI is biased internally to SG with about 100 k Ω .							
	Transmit analog s According to the offollows.		and \overline{FT} , AO is set to va	rious state as an output terminal as				
	FT ME	Transmit LPF	State	of AO				
	"1" "1"	Power On	The output of	MSK Signal				
	"1" "0"	Power on	Transmit LPF	Voice Signal				
	"0" "1"		The Output o	f Receive BPF				
		Power Down	(Used for Dev	vice Test Only)				
	"0" "0"	Power Down	No-signa	al Output				
			(DC-bias	ed to SG)				
AO	TI Mo	du- or	ower down ransmit LPF SG eceive BPF	AO				
	"1" from "0", AO re switched to transr	mains to be connec nit LPF. events AO from out	cted to SG during abou	input digital data on FT changes to ut 12 ms and after that, and AO is signal during transient time from				
Al		ally to SG with abo		Receive BPF and demodulator erial data stream at RD output.				

Name	De	escription					
RD	Demodulated serial data output. This data is synchronized with the re-genera	Demodulated serial data output. This data is synchronized with the re-generated timing clock RT.					
	Receive data timing clock output. This signal is re-generated by internal digition Synchronizing to falling edge of RT, RD is						
RT	RT RD						
	Delay time (RT	$T \rightarrow RD) < 300 \text{ ns}$					
CF	Receive data timing clock is re-generated by digital PLL of which phase correcting speed can be selected with CF. When a digital "1" is put on CF and phase difference between receive data timing and RT is more than 22.5 degree, phase correcting speed is high. In this case, as the phase difference enters within 22.5 degrees, that speed changes to low immediately. When digital "0" is input to CF, phase correcting speed of PLL remains low regardless of the phase difference. Usually, CF is connected to digital "1".						
СТ	PLL's lock-in characteristics can be select When digital "1" is put on CT, PLL requires hand, when digital "0" is input to CT, PLL can be locked in below 18-bit data.	ted with CT. s max. 50-bit alternative data pattern. On the othe	her				
O1	Equipment	СТ					
	Personal/MCA wireless terminals	"1"					
	MCA wireless bases	"0"					
FT	Control signal for the internal connection of AO. Refer to column AO. When digital "0" is input to this pin, transmit LPF enters in power down mode, but the output buffer operational amplifier remains active.						
V_{DD}		as switched capacitor techniques are utilized. etween V _{DD} and AG, and between V _{DD} and DG are	re				

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Rating	Unit
Power Supply Voltage	V _{DD}	T 0500	-0.3 to 7.0	
Analog Input Voltage *1	V _{IA}	Ta = 25°C V _{IA} With respect to AG and DG -0.3 to V _{DD} + 0.3		
Digital Input Voltage *2	V _{ID}	With respect to Ad and Dd	-0.3 to V _{DD} + 0.3	
Operating Temperature	T _{op}		-25 to 70	°C
Storage Temperature	T _{STG}	_	-55 to 150	

^{*1} TI, AI

RECOMMENDED OPERATING CONDITIONS

	Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage		V_{DD}	With respect to AG and DG	4.75	5	5.25	V
FUW	er Supply Voltage	AG, DG	_	_	0	_] v
Oper	ating Temperature	T _{op}	_	-25	25	70	°C
Cryst	al Resonant Frequency	f _{X'} TAL	_	3.6860	3.6864	3.6868	MHz
Data	Speed	Ts	-	_	1200	_	bit/sec
C1		_	_	_	2.2	_	
C2, (C6	_	_	_	0.1	_	
C3		_	_	_	0.047	_	μF
C4		_	$R_{LX} \ge 100 \text{ k}\Omega$		0.01	_	
C5		_	_	_	0.047	_	
	Frequency Deviation	_	25 ±5°C	-100	_	+100	
stal	Temperature Characteristics	_	At -40°C to +85°C	-100	_	+100	ppm
Crystal	Equivalent Series Resistance		_		_	100	Ω
	Load Capacitance	_	_	_	16	_	pF

^{*2} ME, SD, CF, CT, FT

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ELECTRICAL CHARACTERISTICS

DC and Digital Interface Characteristics

 $(V_{DD} = 5 \text{ V } \pm 5\%, \text{ Ta} = -25^{\circ}\text{C to } 70^{\circ}\text{C})$

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Current	I _{DD}	Normal Operating Mode	_	3	6	mA
Oscilating Frequency	f _{MCK}	f _{X'TAL} = 3.6864 MHz ±0.01%	3.6857	3.6864	3.6871	MHz
Input Lookaga Current *1	I _{IL}	$V_{IN} = 0 V$	-10	_	10	μΑ
Input Leakage Current *1	I _{IH}	$V_{IN} = V_{DD}$	-10	_	10	μΑ
lanut Valtana *4	V _{IL}	_	0	_	0.8	
Input Voltage *1	V _{IH}	_	2.2	_	V_{DD}	
Output Voltage *2	V _{OL1}	$I_{0L} = 1.6 \text{ mA}$	0	_	0.4	V
Output Voltage *2	V _{OH1}	$I_{OH} = 400 \mu A$	0.8V _{DD}	_	V_{DD}	V
Output Voltage *3	V _{0L2}	$R_L > 50 \text{ k}\Omega$	0	_	0.4	
	V _{0H2}	C _L < 20 pF	0.6V _{DD}	_	V_{DD}	

^{*1} ME, SD, CF, CT, \overline{FT}

Analog Interface Characteristics

Transmit signal output (AO)

 $(V_{DD} = 5.0 \text{ V } \pm 5\%, \text{ Ta} = -25^{\circ}\text{C to } 70^{\circ}\text{C})$

Parameter	Symbol	Con	dition	Min.	Тур.	Max.	Unit
Carrier Frequency	f _M	SD = "1"	FT = "1"	1199	1200	1201	Hz
- Carrier Frequency	fs	SD = "0"	ME = "1"	1799	1800	1801	I IZ
Carrier Level	V _{OX}	$\begin{array}{c} R_L \geq 100 \; k\Omega \\ C_L \leq 40 \; pF \end{array}$	FT = "1" ME = "1"	-2	0	+2	dBm
Output Resistance	R _{OX}	f _{AO} ≤ 4 kHz		_	_	1	kΩ
Output Load Resistance	R _{LX}	-	_		_	_	K22
Output Load Capacitance	C _{LX}	_		_	_	40	pF
Output DC Voltage	V _{OSX}	-	_		$\frac{V_{DD}}{2}$	$\frac{V_{DD}}{2} + 0.1$	V

Note 0 dBm = 0.775 Vrms

^{*2} ST, RD, RT

^{*3} MCK (NC: MSM6948V)

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Voice signal input (TI)

Parameter	Symbol	Con	Min.	Тур.	Max.	Unit	
Voltage Gain	GT	V _{AO} /V _{TI}	 "4"	-2	0	+2	dB
Input Signal Level	V _{TI}	_	FT = "1" ME = "0"	_	_	0	dBm
Input Resistance	R _{TI}	f _{Tl} ≤ 4 kHz	IVIL – U	50	_	_	kΩ

Built-in signal ground (SG)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
DC Voltage	V _{SG}	Without DC Load	$\frac{V_{DD}}{2} - 0.1$	$\frac{V_{DD}}{2}$	$\frac{V_{DD}}{2} + 0.1$	V

Receive signal input (AI)

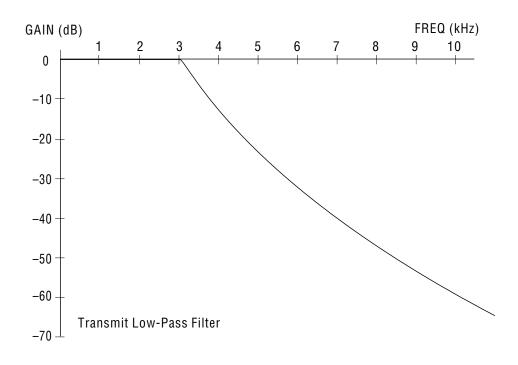
Parameter	Symbol	Condit	Min.	Тур.	Max.	Unit	
Input Resistance	R _{IR}	$f_{TI} \le 4 I$	50	_	_	kΩ	
Receive Signal Level	V _{IR}	—		-30	_	0	dBm
Bit Error Rate	BER	S/N	8 dB	_	1 × 10 ⁻³	_	N/N
	DLN	at AI	10 dB	_	5 × 10 ⁻⁵	_	- IN/IN

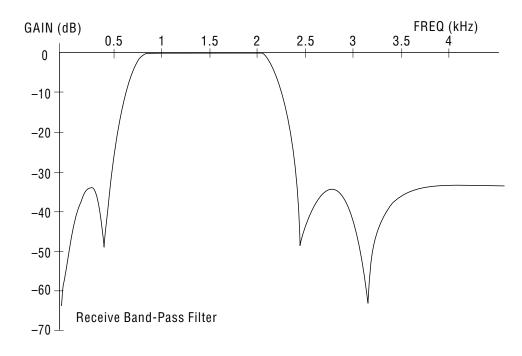
Re-generated receive data timing clock output (RT)

Parameter	Symbol	Condition			Min.	Тур.	Max.	Unit
Data Bit Number for PLL'	N _{PLL1}	CE _ "1"	CT= "0"	*1	_		18	bit
Lock-in	N _{PLL2}	GF	CT= "1"	'	_	_	50	Dit

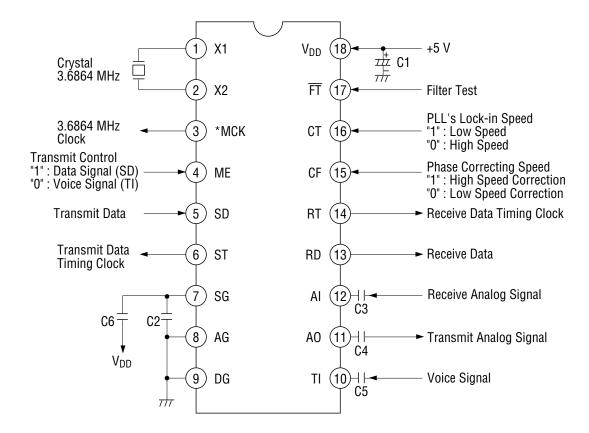
^{*1} Data bit number to lock-in within 22.5 degree

BUILT-IN FILTER FREQUENCY CHARACTERISTICS





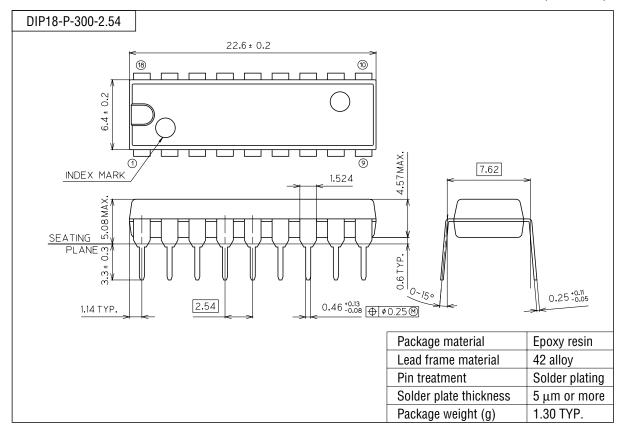
APPLICATION CIRCUIT



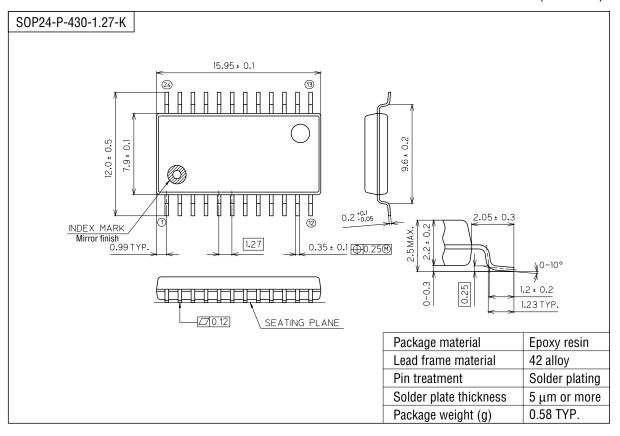
*NC: MSM6948V

PACKAGE DIMENSIONS

(Unit: mm)



(Unit: mm)



Notes for Mounting the Surface Mount Type Package

The SOP, QFP, TSOP, SOJ, QFJ (PLCC), SHP and BGA are surface mount type packages, which are very susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact Oki's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).